Schottky Barrier Diodes BAT54H

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- Device Marking: JV
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS (T_J = $125^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1)	PD		
$T_A = 25^{\circ}C$ Derate above 25°C		200 1.6	m₩ mW/°C
Forward Current (DC)	١ _F	200 Max	mA
Non-Repetitive Peak Forward Current, t _p < 10 msec	I _{FSM}	600	mA
Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66%	I _{FRM}	300	mA
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to150	°C

1. FR-4 Minimum Pad

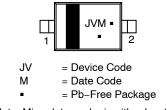
*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

30 VOLT SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES





MARKING DIAGRAM



(Note: Microdot may be in either location)

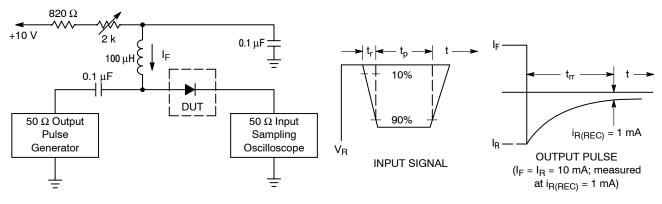
ORDERING INFORMATION

Device	Package	Shipping [†]
BAT54HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
NSVBAT54HT1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAT54H

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \ \mu A$)	V _{(BR)R}	30	_	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	CT	-	7.6	10	pF
Reverse Leakage (V _R = 25 V)	۱ _R	_	0.5	2.0	μAdc
Forward Voltage $(I_F = 0.1 \text{ mA})$ $(I_F = 1.0 \text{ mA})$ $(I_F = 10 \text{ mA})$ $(I_F = 30 \text{ mA})$ $(I_F = 100 \text{ mA})$	V _F	- - - -	0.22 0.29 0.35 0.41 0.52	0.24 0.32 0.40 0.50 0.80	V
Reverse Recovery Time ($I_F = I_R = 10$ mAdc, $I_{R(REC)} = 1.0$ mAdc) Figure 1	t _{rr}	-	_	5.0	ns



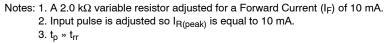
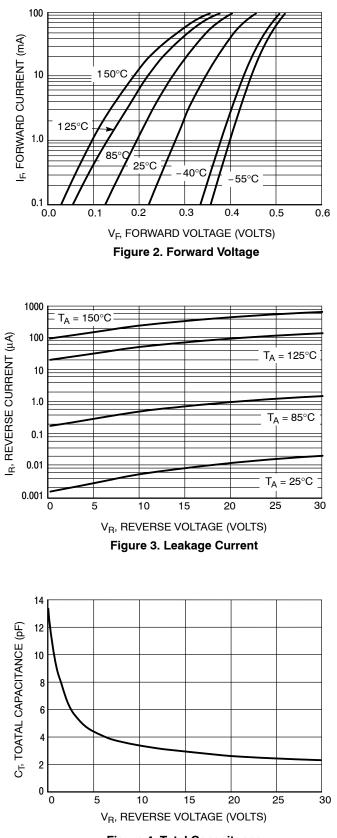


Figure 1. Recovery Time Equivalent Test Circuit

BAT54H



MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

2

nsem



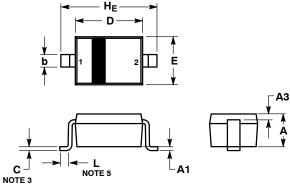


SOD-323 CASE 477-02 **ISSUE H**

NO POLARITY

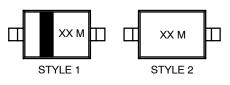
DATE 13 MAR 2007





STYLE 1: STYLE 2: PIN 1. CATHODE (POLARITY BAND) 2. ANODE

GENERIC **MARKING DIAGRAM***



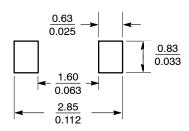
- XX = Specific Device Code M = Date Code
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

- VOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- WITH SOLDER PLATING.
 A. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
Е	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H _E	2.30	2.50	2.70	0.090	0.098	0.105

RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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